

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Forward Voltage @ I _F = 10mA	V _F	0.9	V

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 6)	P _D	300	mW
Power Dissipation (Note 7)	P _D	350	mW
Thermal Resistance, Junction to Ambient Air (Note 6)	R _{θJA}	417	°C/W
Thermal Resistance, Junction to Ambient Air (Note 7)	R _{θJA}	357	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-65 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Type Number	Marking Code	Zener Voltage Range (Note 8)				Maximum Zener Impedance f = 1KHz			Maximum Reverse Current (Note 8)		Temperature Coefficient @ I _{ZT} mV/°C	
		V _Z @ I _{ZT}			I _{ZT}	Z _{1T} @ I _{ZT}	Z _{ZK} @ I _{ZK}		I _R	V _R	Min	Max
		Nom (V)	Min (V)	Max (V)	(mA)	(Ω)	(Ω)	(mA)	(μA)	(V)		
BZX84C2V4	ZB	2.4	2.2	2.6	5.0	100	600	1.0	50	1.0	-3.5	0
BZX84C2V7	ZC	2.7	2.5	2.9	5.0	100	600	1.0	20	1.0	-3.5	0
BZX84C3V0	ZD	3.0	2.8	3.2	5.0	95	600	1.0	10	1.0	-3.5	0
BZX84C3V3	ZE	3.3	3.1	3.5	5.0	95	600	1.0	5.0	1.0	-3.5	0
BZX84C3V6	ZF	3.6	3.4	3.8	5.0	90	600	1.0	5.0	1.0	-3.5	0
BZX84C3V9	ZG	3.9	3.7	4.1	5.0	90	600	1.0	3.0	1.0	-3.5	0
BZX84C4V3	ZH	4.3	4.0	4.6	5.0	90	600	1.0	3.0	1.0	-3.5	0
BZX84C4V7	Z1	4.7	4.4	5.0	5.0	80	500	1.0	3.0	2.0	-3.5	0.2
BZX84C5V1	Z2	5.1	4.8	5.4	5.0	60	480	1.0	2.0	2.0	-2.7	1.2
BZX84C5V6	Z3	5.6	5.2	6.0	5.0	40	400	1.0	1.0	2.0	-2.0	2.5
BZX84C6V2	Z4	6.2	5.8	6.6	5.0	10	150	1.0	3.0	4.0	0.4	3.7
BZX84C6V8	Z5	6.8	6.4	7.2	5.0	15	80	1.0	2.0	4.0	1.2	4.5
BZX84C7V5	Z6	7.5	7.0	7.9	5.0	15	80	1.0	1.0	5.0	2.5	5.3
BZX84C8V2	Z7	8.2	7.7	8.7	5.0	15	80	1.0	0.7	5.0	3.2	6.2
BZX84C9V1	Z8	9.1	8.5	9.6	5.0	15	100	1.0	0.5	6.0	3.8	7.0
BZX84C10	Z9	10	9.4	10.6	5.0	20	150	1.0	0.2	7.0	4.5	8.0
BZX84C11	Y1	11	10.4	11.6	5.0	20	150	1.0	0.1	8.0	5.4	9.0
BZX84C12	Y2	12	11.4	12.7	5.0	25	150	1.0	0.1	8.0	6.0	10.0
BZX84C13	Y3	13	12.4	14.1	5.0	30	170	1.0	0.1	8.0	7.0	11.0
BZX84C15	Y4	15	13.8	15.6	5.0	30	200	1.0	0.1	10.5	9.2	13.0
BZX84C16	Y5	16	15.3	17.1	5.0	40	200	1.0	0.1	11.2	10.4	14.0
BZX84C18	Y6	18	16.8	19.1	5.0	45	225	1.0	0.1	12.6	12.4	16.0
BZX84C20	Y7	20	18.8	21.2	5.0	55	225	1.0	0.1	14.0	14.4	18.0
BZX84C22	Y8	22	20.8	23.3	5.0	55	250	1.0	0.1	15.4	16.4	-
BZX84C24	Y9	24	22.8	25.6	5.0	70	250	1.0	0.1	16.8	18.4	-
BZX84C27	YA	27	25.1	28.9	2.0	80	300	0.5	0.1	18.9	21.4	-
BZX84C30	YB	30	28.0	32.0	2.0	80	300	0.5	0.1	21.0	24.4	-
BZX84C33	YC	33	31.0	35.0	2.0	80	325	0.5	0.1	23.1	27.4	-
BZX84C36	YD	36	34.0	38.0	2.0	90	350	0.5	0.1	25.2	30.4	-
BZX84C39	YE	39	37.0	41.0	2.0	130	350	0.5	0.1	27.3	33.4	-
BZX84C43	YF	43	40.0	46.0	2.0	150	375	0.5	0.1	30.1	37.6	-
BZX84C47	YG	47	44.0	50.0	2.0	170	375	0.5	0.1	32.9	42.0	-
BZX84C51	YH	51	48.0	54.0	2.0	180	400	0.5	0.1	35.7	46.6	-

- Notes: 6. Device mounted on FR-4 PC board with recommended pad layout, which can be found on our website at <http://www.diodes.com>.
7. Valid provided the terminals are kept at ambient temperature.
8. Short duration pulse test used to minimize self-heating effect.

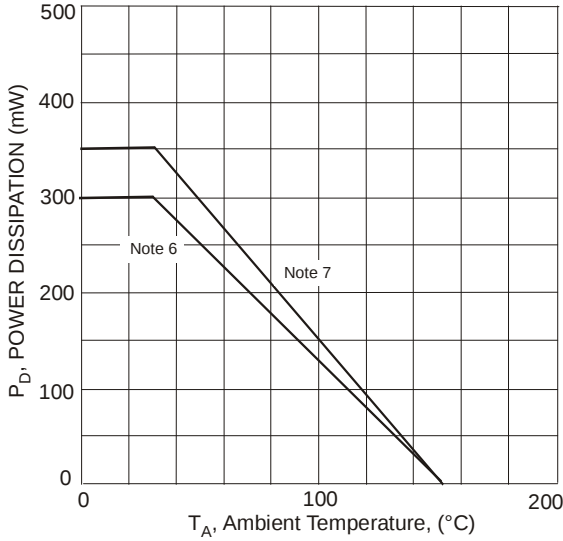


Fig. 1 Power Derating Curve

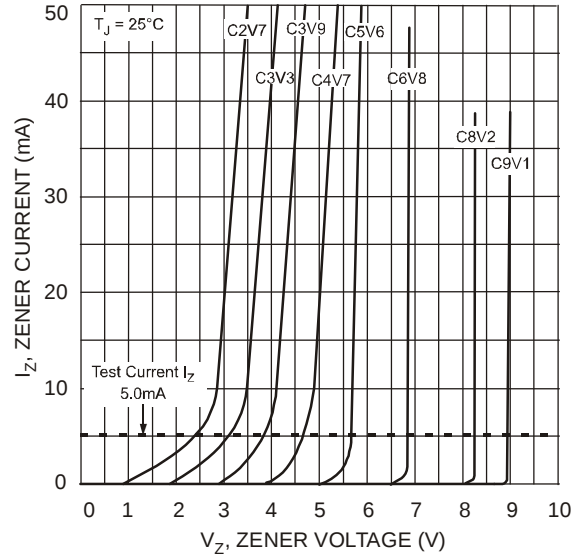


Fig. 2 Typical Zener Breakdown Characteristics

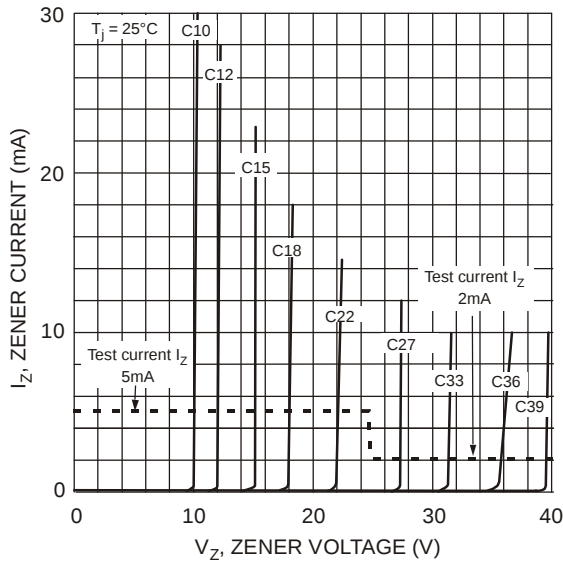


Fig. 3 Typical Zener Breakdown Characteristics

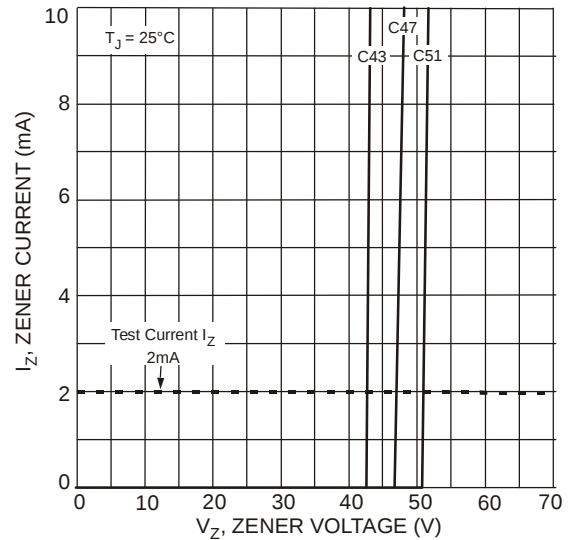


Fig. 4 Typical Zener Breakdown Characteristics

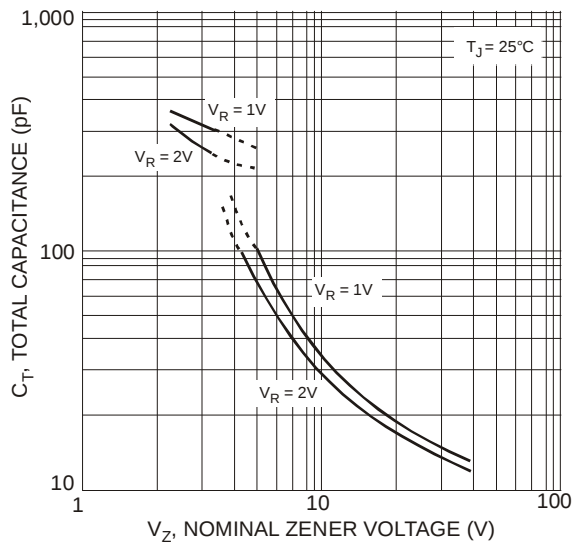


Fig. 5 Typical Total Capacitance vs. Nominal Zener Voltage

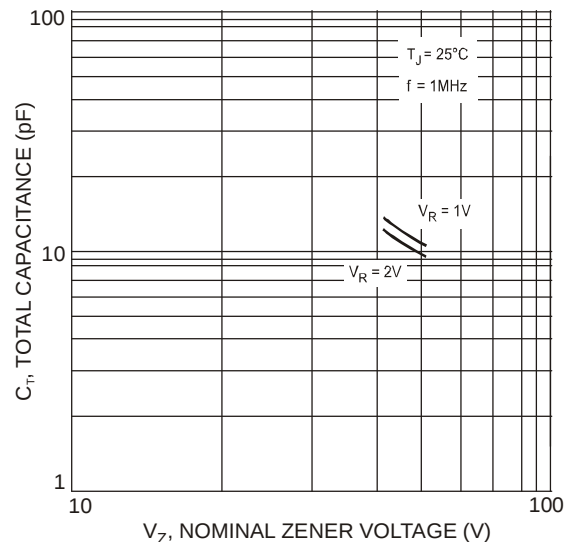
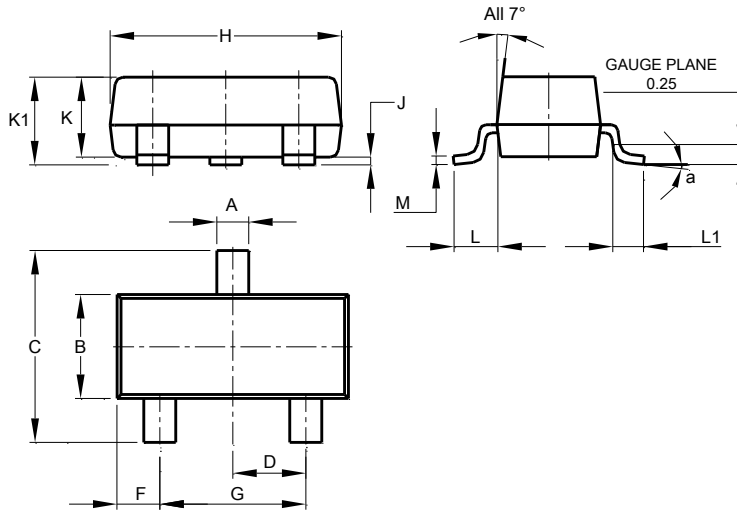


Fig. 6 Typical Total Capacitance vs. Nominal Zener Voltage

Package Outline Dimensions

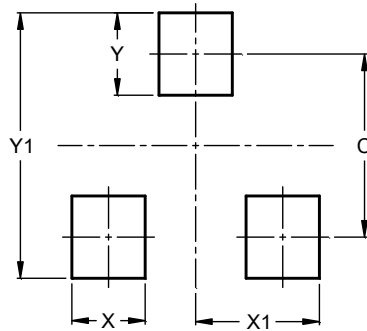
Please see <http://www.diodes.com/package-outlines.html> for the latest version.



SOT23			
Dim	Min	Max	Typ
A	0.37	0.51	0.40
B	1.20	1.40	1.30
C	2.30	2.50	2.40
D	0.89	1.03	0.915
F	0.45	0.60	0.535
G	1.78	2.05	1.83
H	2.80	3.00	2.90
J	0.013	0.10	0.05
K	0.890	1.00	0.975
K1	0.903	1.10	1.025
L	0.45	0.61	0.55
L1	0.25	0.55	0.40
M	0.085	0.150	0.110
a	0°	8°	--
All Dimensions in mm			

Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.



Dimensions	Value (in mm)
C	2.0
X	0.8
X1	1.35
Y	0.9
Y1	2.9

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